

What is claimed is:

1. A plating apparatus comprising:

5 a plating unit having a plating bath for holding a plating liquid therein;

10 a plating liquid monitoring unit having a liquid chromatography device for separating and quantifying an additive in a sample of the plating liquid, and an arithmetical unit for comparing a quantified value of said additive with a given concentration predetermined for said additive and producing an output signal representing the compared result; and

15 an additive replenishing unit for adding a solution including said additive from an additive tank to the plating liquid in said plating bath based on said output signal from said arithmetical unit in said plating liquid monitoring unit.

20 2. A plating apparatus according to claim 1, wherein said liquid chromatography device comprises an evaporative light-scattering detector for quantifying said additive.

25 3. A plating apparatus according to claim 1, wherein said plating liquid comprises a sulfuric acid copper plating liquid for embedding copper in a fine recess defined in a substrate to form an interconnection; and

ionic components are removed from said plating liquid in advance before said additive is quantified.

4. A plating apparatus according to claim 1,
wherein said additive comprises at least one of an oxygen-
containing water-soluble polymeric compound, a sulfur-
5 containing organic compound, and a nitrogen-containing organic
compound.

5. A method of managing a plating liquid
composition, comprising:
10 sampling a plating liquid in a plating bath;
separating and quantifying an additive in the
sampled plating liquid with liquid chromatography;
comparing a quantified value of said additive with
a given concentration predetermined for said additive; and
15 adding a solution including said additive to said
plating liquid based on the compared result.

6. A method of managing a plating liquid
composition according to claim 5, further comprising removing
20 ionic components from said plating liquid in advance before
said additive is quantified.